

### Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	15	V
Collector-Emitter Voltage	V <sub>CEO</sub>	15	V
Emitter-Base Voltage	V <sub>EBO</sub>	5	V
Base Current	IB	500	mA
Continuous Collector Current	lc	4	A
Peak Pulse Collector Current	I <sub>CM</sub>	13	A

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)		1.1 8.8	W mW/°C	
Linear Derating Factor	(Note 6)	– P <sub>D</sub>	1.7 13.6		
(Note 5)		P	113		
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>0JA</sub>	73	°C/W	
Thermal Resistance, Junction to Lead	(Note 7)	R <sub>θJL</sub>	18.6		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

## ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

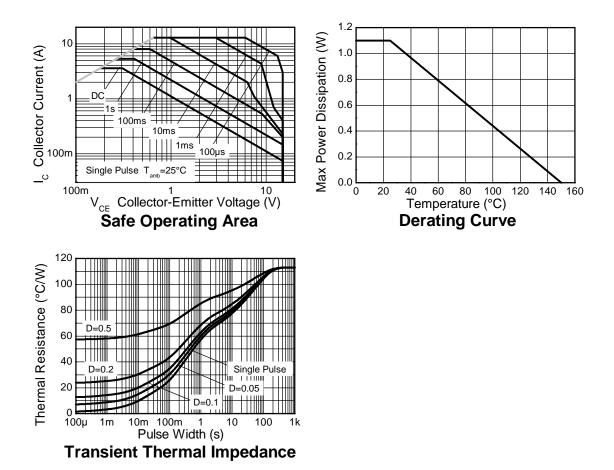
5. For a device mounted with the collector lead on 25mm x 25mm 1oz copper that is on single-sided 1.6mm FR4 PCB; device is measured under still air Notes: conditions whilst operating in a steady-state.

6. Same as Note 6, except the device is measured at t  $\leq$  5 sec.

Thermal resistance from junction to solder-point (at the end of the collector lead).
Refer to JEDEC specification JESD22-A114 and JESD22-A115.



## **Thermal Characteristics and Derating Information**





ZXT10N15DE6

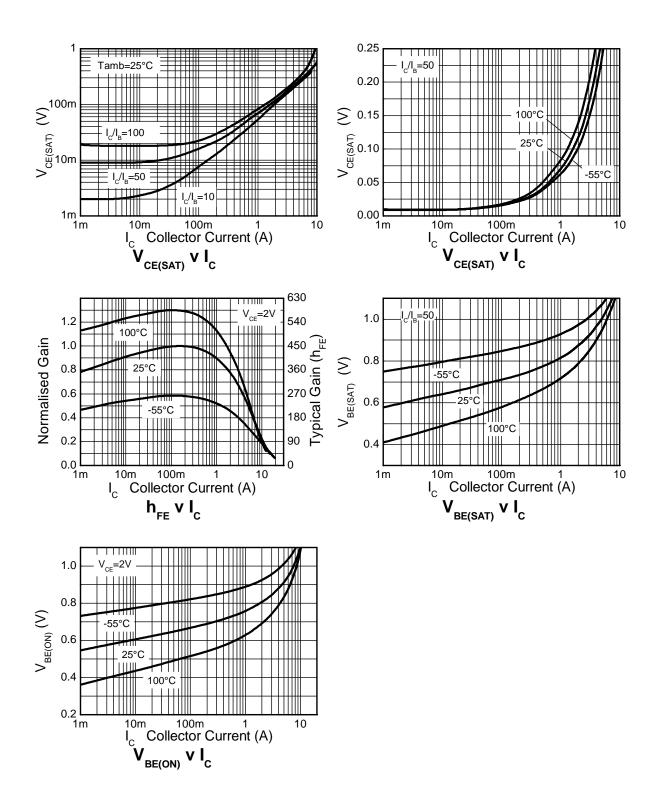
<b>Electrical Characteristics</b> (@T <sub>A</sub> = +25°C, unless otherwise specified.)
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			-			
	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS	1			1	1	Γ
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	15	70	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	15	18		V	$I_{\rm C} = 10 {\rm mA}$
Emitter-Base Breakdown Voltage	BVEBO	5	8.2	—	V	I <sub>E</sub> = 100μA
Collector-Base Cutoff Current	ICBO	—	—	100	nA	$V_{CB} = 10V$
Emitter Cutoff Current	I <sub>EBO</sub>	—	—	100	nA	$V_{EB} = 4V$
Collector-Emitter Cutoff Current	I <sub>CES</sub>	_	—	100	nA	$V_{CES} = 10V$
ON CHARACTERISTICS (Note 9)						
DC Current Gain		200	415			$I_{C} = 10 \text{mA}, V_{CE} = 2 \text{V}$
	hFE	300	450	_		$I_{C} = 0.2A, V_{CE} = 2V$
		200	320	_	_	$I_C = 3A, V_{CE} = 2V$
		150	240	_		$I_C = 5A, V_{CE} = 2V$
		_	80	_		$I_{C} = 12A, V_{CE} = 2V$
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_	8	14	mV	$I_{\rm C} = 100 {\rm mA}, I_{\rm B} = 10 {\rm mA}$
		_	70	100		$I_{\rm C} = 1$ A, $I_{\rm B} = 10$ mA
		_	165	200		$I_{C} = 3A, I_{B} = 50mA$
		_	230	260		$I_{C} = 4A, I_{B} = 50mA$
Base-Emitter Turn-On Voltage	V <sub>BE(sat)</sub>	_	0.94	1	V	$I_{C} = 4A, I_{B} = 50mV$
Base-Emitter Turn-On Voltage	V <sub>BE(on)</sub>	_	0.87	0.95	V	$I_C = 4A, V_{CE} = 2V$
SMALL SIGNAL CHARACTERISTICS						·
Current Gain-Bandwidth Product	fT	80	120		MHz	V <sub>CE</sub> = 10V, I <sub>C</sub> = 50mA, f = 100MHz
Output Capacitance	Cobo		30	40	pF	V <sub>CB</sub> = 10V, f = 1MHz
Turn-On Time	t <sub>(on)</sub>	_	120		ns	V <sub>CC</sub> = 10V, I <sub>C</sub> = 3A
Turn-Off Time	t <sub>(off)</sub>	_	160		ns	$I_{B1} = I_{B2} = 50 \text{mA}$

Note: 9. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.



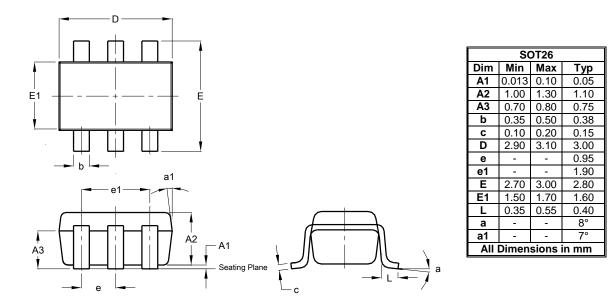
### Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)





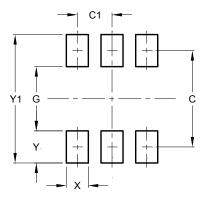
### **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



## Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



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